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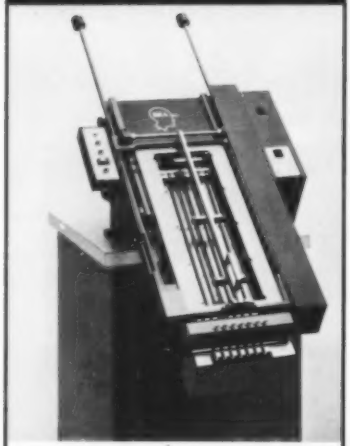

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IDEA Inc.

Leaders in Burn-in Automation

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(213) 320-9462

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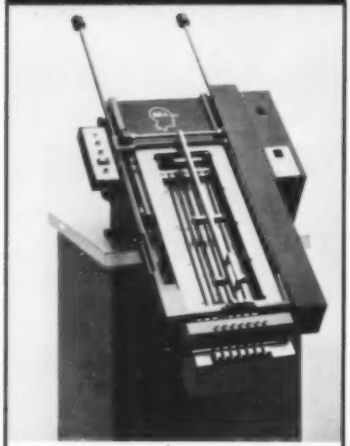

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